SLOVENSKI STANDARD
SIST EN IEC 61249-2-51:2023

01-september-2023

Materiali za plošče tiskanih vezij in druge povezovalne strukture - 2-51. del: Ojačeni laminati z bakreno folijo in brez nje - Osnovni materiali za nosilne trakove kartic integriranih vezij, neprevlečeni

Materials for printed boards and other interconnecting structures - Part 2-51: Reinforced base materials, clad and unclad - Base materials for Integrated Circuit card carrier tape, unclad

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Werkstoffe für Leiterplatten und andere Verbindungsstrukturen – Teil 2-51: Verstärkte Basismaterialien, kaschiert und nicht kaschiert – Basismaterialien für Trägerbänder für integrierte Schaltungen, nicht kaschiert

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Matériaux pour circuits imprimés et autres structures d'interconnexion - Partie 2-51: Matériaux de base renforcés, recouverts ou non - Matériaux de base pour bande support de carte à circuit intégré, non recouverts

Ta slovenski standard je istoveten z: EN IEC 61249-2-51:2023

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards

SIST EN IEC 61249-2-51:2023 en

2003-01.Slovenski inštitut za standardizacijo. Razmnoževanje celote ali delov tega standarda ni dovoljeno.

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 61249-2-51

June 2023

ICS 31.180

English Version

Materials for printed boards and other interconnecting structures - Part 2-51: Reinforced base materials, clad and unclad - Base materials for integrated circuit card carrier tape, unclad (IEC 61249-2-51:2023)

Matériaux pour circuits imprimés et autres structures d'interconnexion - Partie 2-51: Matériaux de base renforcés, plaqués et non plaqués - Matériaux de base pour bande support de carte à circuit intégré, non plaqués (IEC 61249-2-51:2023)

Werkstoffe für Leiterplatten und andere Verbindungsstrukturen - Teil 2-51: Kaschierte und unkaschierte verstärkte Basismaterialien - Basismaterial als Chipträger, nicht kaschiert (IEC 61249-2-51:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Ref. No. EN IEC 61249-2-51:2023 E

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European foreword

The text of document 91/1847/FDIS, future edition 1 of IEC 61249-2-51, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61249-2-51:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2024-03-15
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2026-06-15

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The text of the International Standard IEC 61249-2-51:2023 was approved by CENELEC as a European Standard without any modification.

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

ISO 9000 NOTE Approved as EN ISO 9000

ISO 14001 NOTE Approved as EN ISO 14001

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 61189-2	2006	Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2: Test methods for materials for interconnection structures	EN 61189-2	2006
IEC/PAS 61249-6-3	-	Specification for finished fabric woven from "E" glass for printed boards	-	-
ISO 2813	-	Paints and varnishes - Determination of gloss value at 20°, 60° and 85°	EN ISO 2813	-
ISO 8296	-	Plastics - Film and sheeting - Determination of wetting tension	-	-
ISO 11014	2009	Safety data sheet for chemical products - Content and order of sections	-	-
ISO 21920-2	-	Geometrical product specifications (GPS) - Surface texture: Profile - Part 2: Terms, definitions and surface texture parameters	EN ISO 21920-2	-
ASTM D 882	-	Standard Test Method for Tensile Properties of Thin Plastic Sheeting	-	-

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https://standards.iteh.ai/catalog/standards/sist/e36d36d3-b315-4b02-8c51-0d71e120d10d/sist-en-iec-61249-2-51-2023

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

Materials for printed boards and other interconnecting structures – Part 2-51: Reinforced base materials, clad and unclad – Base materials for integrated circuit card carrier tape, unclad

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CONTENTS

iTeh STANDARD PREVIEW
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SIST EN IEC 61249-2-51:2023
https://standards.iteh.ai/catalog/standards/sist/e36d36d3-b315-4b02-8c51-0d71c120d10d/sist-en-iec-61249-2-51-2023

SIST EN IEC 61249-2-51:2023

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https://standards.iteh.ai/catalog/standards/sist/e36d36d3-b315-4b02-8c51-0d71e120d10d/sist-en-iec-61249-2-51-2023

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 2-51: Reinforced base materials clad and unclad – Base materials for integrated circuit card carrier tape, unclad

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The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1847/FDIS	91/1865/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

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This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61249 series, published under the general title *Materials for printed boards and other interconnecting structures*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
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SIST EN IEC 61249-2-51:2023
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